

Specification Sheet

Metallic Copper Foamposite

(Cu, PPI-50PPI, Thickness; 2mm)

Stock No: NS6130-10-1007, CAS: 7440-50-8

Product	:	Metallic Copper Foamposite
Stock No	:	NS6130-10-1007
CAS	:	7440-50-8
Purity	:	>99.8%
Dimension	:	500mm X 500mm
Thickness	:	2mm
PPI	:	50
Porosity	:	>70%
Molecular Formula	:	Cu
Molecular Weight	:	63.55g/mol
Density	:	8.96g/cm ³
Melting Point	:	1085°C
Boiling Point	:	2562°C
Thermal Expansion	:	16.5μm.m-1.k-1
Thermal Conductivity	:	401W.m-1.k-1
Tensile Strength	:	1.25N/mm
Young's modulus	:	110-128GPa
Shear strength	:	190Psi
Vickers hardness	:	369MPa
Poisson's ratio	:	0.34
Electrical resistivity	:	1.673μΩ-cm
Specific heat	:	0.39kj/kgK
Electronegativity	:	1.90paulings
Heat of fusion	:	13.26kJ.mol-1
Heat of vaporization	:	300.4kJ.mol-1
Main Inspect Verifier	:	Manager QC

NANOSHEL LLC (In Collaboration)

3422 Old Capitol Trial Suit 1305, Wilmington DE - 19808 USA
(001) 302 652-3464, + 91 9779-880077

Note: Product Specification are subject to amendment and may change over time



Characterization of Metallic Copper Foamposite



Metallic Copper Foamposite



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